

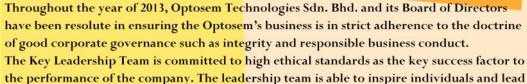
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**Quarter 4'2013** 



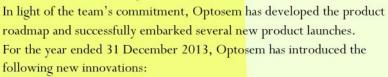
## OPEN CAVITY PREMOLDED LEAD FRAME FOR MEMS



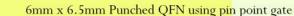


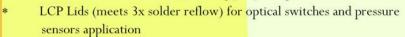
by example in their daily work, which geared towards results and performance.

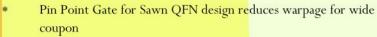
## **Business Sustainability**











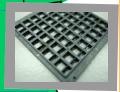


Custom Formulated resin for improved adhesion for good package integrity.





NEW... Cover for Proximity, Pressure Sensor



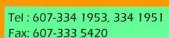
APPLICATION IN OPTICAL SWITCHES, RF MEMS,
PRESSURE SENSORS, GYROSCOPE, PASSIVE INFRA SENSORS.

**OPTOSEM TECHNOLOGIES SDN BHD.** Established in Johor, Malaysia in 2002, OPTOSEM specialize on the design and molding of Open Cavity IC Packages. Development in Injection Molding Process of QFN packages opens up the market for

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